

# Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Supply, Demand and Key Producers, 2026-2032

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## Abstracts

The global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market size is expected to reach \$ 756 million by 2032, rising at a market growth of 10.6% CAGR during the forecast period (2026-2032).

An automotive-grade copper needle-type (pin-fin) heat dissipation substrate is a direct-cooled copper baseplate attached to the bottom of IGBT/SiC power modules. It features a pin-fin array formed on the coolant side so coolant can impinge/flow directly over the copper surface, often reducing or eliminating an intermediate thermal-grease layer, lowering thermal resistance and enabling higher power density in traction inverters and other high heat-flux automotive power electronics.

Upstream inputs include copper stock (bars/billets), anti-corrosion plating systems (e.g., Ni/Ag), brazing/sealing consumables, and forming/machining equipment with tooling. Midstream value is driven by pin-fin formation (cold precision forging and/or precision machining), surface finishing, and metrology & reliability inspection with full lot traceability. Downstream, the baseplate is co-designed with module packaging and integrated by Tier-1s into traction inverters.

In 2025, global automotive-grade power semiconductor modules copper needle type heat dissipation substrate production reached approximately 33 million units, with an average global market price is \$10 per unit.

A copper needle-type heat dissipation substrate for automotive-grade power semiconductor modules is a critical thermal-path component designed for high heat-flux devices such as IGBTs and SiC MOSFETs. It typically features dense copper pins formed on a copper base, and is coupled with a liquid-cooling cavity or cold-plate architecture to dramatically increase heat-transfer area and enhance convection.

Beyond 'running cooler,' its system value is enabling higher power density, more compact cooling hardware, improved transient thermal response, and better lifetime margins under demanding duty cycles?making it a prominent structural route as electrified powertrains move toward higher voltage, higher switching frequency, and higher integration.

Technology evolution is driven by three major vectors. First, engineering optimization of pin geometry and flow management (pin density/height/arrangement, inlet distribution, boundary-layer disruption) to balance thermal resistance against pressure drop and pumping losses. Second, manufacturing and joining reliability?whether the pin field is integral to the base or created via high-reliability joining?plus robust surface treatments and tight dimensional/flatness control for consistent module assembly. Third, automotive lifetime failure-mechanism control, focusing on thermo-mechanical fatigue under thermal/power cycling, corrosion/electrochemical risks in coolant environments, and sensitivity to contamination and blockage over long service life. As SiC and high power-density e-drives scale, copper pin-fin substrates increasingly function as a co-engineered thermal?fluid?mechanical platform rather than a standalone 'metal part,' requiring tight coordination with the cooling loop, TIM, and module packaging stack. Opportunities are anchored in the rising thermal demand of electrified powertrains?higher voltage platforms, higher power density, and more integrated e-axle architectures?which amplifies the need for enhanced liquid-side heat transfer. Copper pin-fin substrates are well positioned where 'high heat flux + liquid cooling' dominates, supporting downsizing and efficiency targets. Platform standardization can also drive geometry standardization, tighter process windows, and improved cost curves, rewarding suppliers with strong cross-domain engineering and validation capabilities. This report studies the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate that contribute to its increasing demand across many markets.

### **Highlights and key features of the study**

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate total production and demand, 2021-2032, (K Units)

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate total production value, 2021-2032, (USD Million)

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (K Units), (based on production site)

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate consumption by region & country, CAGR, 2021-2032 & (K Units)

U.S. VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate domestic production, consumption, key domestic manufacturers and share

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (K Units)

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate production by Type, production, value, CAGR, 2021-2032, (USD Million) & (K Units)

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate production by Application, production, value, CAGR, 2021-2032, (USD Million) & (K Units)

This report profiles key players in the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Huangshan Gooze, Heatsink Advanced Materials, Kunshan Gootage Thermal Technology, Dana Incorporated, Jentech Precision Industrial, Amulaire Thermal Technology, TAIWA CO., Ltd., Wieland Microcool, Jiangyin Saiying Electron, Suzhou Haoli Electronic Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market

#### **Detailed Segmentation:**

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market, Segmentation by Type:

IGBT Module

SiC MOSFET Module

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market, Segmentation by Manufacturing Process:

Integral Cold Forging

Welding Assembly Forming

Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market, Segmentation by Vehicle:

Passenger Car

Commercial Vehicle

## Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market, Segmentation by Application:

BEV

PHEV

### **Companies Profiled:**

Huangshan Googe

Heatsink Advanced Materials

Kunshan Gootage Thermal Technology

Dana Incorporated

Jentech Precision Industrial

Amulaire Thermal Technology

TAIWA CO., Ltd.

Wieland Microcool

Jiangyin Saiying Electron

Suzhou Haoli Electronic Technology

Sitritec Thermal Control Materials

### **Key Questions Answered:**

1. How big is the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market?
2. What is the demand of the global Automotive-grade Power Semiconductor Modules

Copper Needle Type Heat Dissipation Substrate market?

3. What is the year over year growth of the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market?
4. What is the production and production value of the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market?
5. Who are the key producers in the global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate market?
6. What are the growth factors driving the market demand?

## Contents

### 1 SUPPLY SUMMARY

1.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Introduction

1.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Supply & Forecast

1.2.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value (2021 & 2025 & 2032)

1.2.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032)

1.2.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Pricing Trends (2021-2032)

1.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Region (Based on Production Site)

1.3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Region (2021-2032)

1.3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Region (2021-2032)

1.3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Region (2021-2032)

1.3.4 North America Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032)

1.3.5 Europe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032)

1.3.6 China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032)

1.3.7 Japan Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032)

1.4 Market Drivers, Restraints and Trends

1.4.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Drivers

1.4.2 Factors Affecting Demand

1.4.3 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Major Market Trends

### 2 DEMAND SUMMARY

- 2.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Demand (2021-2032)
- 2.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption by Region
  - 2.2.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption by Region (2021-2026)
  - 2.2.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Forecast by Region (2027-2032)
- 2.3 United States Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.4 China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.5 Europe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.6 Japan Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.7 South Korea Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.8 ASEAN Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)
- 2.9 India Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032)

### **3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS**

- 3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturer (2021-2026)
- 3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Manufacturer (2021-2026)
- 3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Manufacturer (2021-2026)
- 3.4 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Company Evaluation Quadrant
- 3.5 Industry Rank and Concentration Rate (CR)
  - 3.5.1 Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Industry Rank of Major Manufacturers
  - 3.5.2 Global Concentration Ratios (CR4) for Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate in 2025
  - 3.5.3 Global Concentration Ratios (CR8) for Automotive-grade Power Semiconductor

Modules Copper Needle Type Heat Dissipation Substrate in 2025

3.6 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Overall Company Footprint Analysis

3.6.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Region Footprint

3.6.2 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Company Product Type Footprint

3.6.3 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Company Product Application Footprint

3.7 Competitive Environment

3.7.1 Historical Structure of the Industry

3.7.2 Barriers of Market Entry

3.7.3 Factors of Competition

3.8 New Entrant and Capacity Expansion Plans

3.9 Mergers, Acquisition, Agreements, and Collaborations

## **4 UNITED STATES VS CHINA VS REST OF THE WORLD**

4.1 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Comparison

4.1.1 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Comparison (2021 & 2025 & 2032)

4.1.2 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share Comparison (2021 & 2025 & 2032)

4.2 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Comparison

4.2.1 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Comparison (2021 & 2025 & 2032)

4.2.2 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share Comparison (2021 & 2025 & 2032)

4.3 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Comparison

4.3.1 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Comparison (2021 & 2025 & 2032)

4.3.2 United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Market Share Comparison (2021 & 2025 & 2032)

4.4 United States Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers and Market Share, 2021-2026

4.4.1 United States Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (States, Country)

4.4.2 United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value (2021-2026)

4.4.3 United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2026)

4.5 China Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers and Market Share

4.5.1 China Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (Province, Country)

4.5.2 China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value (2021-2026)

4.5.3 China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2026)

4.6 Rest of World Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers and Market Share, 2021-2026

4.6.1 Rest of World Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (State, Country)

4.6.2 Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value (2021-2026)

4.6.3 Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2026)

## **5 MARKET ANALYSIS BY TYPE**

5.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Size Overview by Type: 2021 VS 2025 VS 2032

5.2 Segment Introduction by Type

5.2.1 IGBT Module

### 5.2.2 SiC MOSFET Module

## 5.3 Market Segment by Type

5.3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Type (2021-2032)

5.3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Type (2021-2032)

5.3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Type (2021-2032)

## 6 MARKET ANALYSIS BY MANUFACTURING PROCESS

6.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Size Overview by Manufacturing Process: 2021 VS 2025 VS 2032

### 6.2 Segment Introduction by Manufacturing Process

6.2.1 Integral Cold Forging

6.2.2 Welding Assembly Forming

### 6.3 Market Segment by Manufacturing Process

6.3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Manufacturing Process (2021-2032)

6.3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturing Process (2021-2032)

6.3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Manufacturing Process (2021-2032)

## 7 MARKET ANALYSIS BY VEHICLE

7.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Size Overview by Vehicle: 2021 VS 2025 VS 2032

### 7.2 Segment Introduction by Vehicle

7.2.1 Passenger Car

7.2.2 Commercial Vehicle

### 7.3 Market Segment by Vehicle

7.3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Vehicle (2021-2032)

7.3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Vehicle (2021-2032)

7.3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Vehicle (2021-2032)

## **8 MARKET ANALYSIS BY APPLICATION**

8.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Size Overview by Application: 2021 VS 2025 VS 2032

8.2 Segment Introduction by Application

8.2.1 BEV

8.2.2 PHEV

8.3 Market Segment by Application

8.3.1 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Application (2021-2032)

8.3.2 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Application (2021-2032)

8.3.3 World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Application (2021-2032)

## **9 COMPANY PROFILES**

9.1 Huangshan Googe

9.1.1 Huangshan Googe Details

9.1.2 Huangshan Googe Major Business

9.1.3 Huangshan Googe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.1.4 Huangshan Googe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.1.5 Huangshan Googe Recent Developments/Updates

9.1.6 Huangshan Googe Competitive Strengths & Weaknesses

9.2 Heatsink Advanced Materials

9.2.1 Heatsink Advanced Materials Details

9.2.2 Heatsink Advanced Materials Major Business

9.2.3 Heatsink Advanced Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.2.4 Heatsink Advanced Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.2.5 Heatsink Advanced Materials Recent Developments/Updates

9.2.6 Heatsink Advanced Materials Competitive Strengths & Weaknesses

9.3 Kunshan Gootage Thermal Technology

- 9.3.1 Kunshan Gootage Thermal Technology Details
- 9.3.2 Kunshan Gootage Thermal Technology Major Business
- 9.3.3 Kunshan Gootage Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
- 9.3.4 Kunshan Gootage Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 9.3.5 Kunshan Gootage Thermal Technology Recent Developments/Updates
- 9.3.6 Kunshan Gootage Thermal Technology Competitive Strengths & Weaknesses
- 9.4 Dana Incorporated
  - 9.4.1 Dana Incorporated Details
  - 9.4.2 Dana Incorporated Major Business
  - 9.4.3 Dana Incorporated Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
  - 9.4.4 Dana Incorporated Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 9.4.5 Dana Incorporated Recent Developments/Updates
  - 9.4.6 Dana Incorporated Competitive Strengths & Weaknesses
- 9.5 Jentech Precision Industrial
  - 9.5.1 Jentech Precision Industrial Details
  - 9.5.2 Jentech Precision Industrial Major Business
  - 9.5.3 Jentech Precision Industrial Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
  - 9.5.4 Jentech Precision Industrial Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 9.5.5 Jentech Precision Industrial Recent Developments/Updates
  - 9.5.6 Jentech Precision Industrial Competitive Strengths & Weaknesses
- 9.6 Amulaire Thermal Technology
  - 9.6.1 Amulaire Thermal Technology Details
  - 9.6.2 Amulaire Thermal Technology Major Business
  - 9.6.3 Amulaire Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
  - 9.6.4 Amulaire Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 9.6.5 Amulaire Thermal Technology Recent Developments/Updates
  - 9.6.6 Amulaire Thermal Technology Competitive Strengths & Weaknesses

## 9.7 TAIWA CO., Ltd.

9.7.1 TAIWA CO., Ltd. Details

9.7.2 TAIWA CO., Ltd. Major Business

9.7.3 TAIWA CO., Ltd. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.7.4 TAIWA CO., Ltd. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.7.5 TAIWA CO., Ltd. Recent Developments/Updates

9.7.6 TAIWA CO., Ltd. Competitive Strengths & Weaknesses

## 9.8 Wieland Microcool

9.8.1 Wieland Microcool Details

9.8.2 Wieland Microcool Major Business

9.8.3 Wieland Microcool Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.8.4 Wieland Microcool Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.8.5 Wieland Microcool Recent Developments/Updates

9.8.6 Wieland Microcool Competitive Strengths & Weaknesses

## 9.9 Jiangyin Saiying Electron

9.9.1 Jiangyin Saiying Electron Details

9.9.2 Jiangyin Saiying Electron Major Business

9.9.3 Jiangyin Saiying Electron Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.9.4 Jiangyin Saiying Electron Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.9.5 Jiangyin Saiying Electron Recent Developments/Updates

9.9.6 Jiangyin Saiying Electron Competitive Strengths & Weaknesses

## 9.10 Suzhou Haoli Electronic Technology

9.10.1 Suzhou Haoli Electronic Technology Details

9.10.2 Suzhou Haoli Electronic Technology Major Business

9.10.3 Suzhou Haoli Electronic Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

9.10.4 Suzhou Haoli Electronic Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.10.5 Suzhou Haoli Electronic Technology Recent Developments/Updates

- 9.10.6 Suzhou Haoli Electronic Technology Competitive Strengths & Weaknesses
- 9.11 Sitritec Thermal Control Materials
  - 9.11.1 Sitritec Thermal Control Materials Details
  - 9.11.2 Sitritec Thermal Control Materials Major Business
  - 9.11.3 Sitritec Thermal Control Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
  - 9.11.4 Sitritec Thermal Control Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 9.11.5 Sitritec Thermal Control Materials Recent Developments/Updates
  - 9.11.6 Sitritec Thermal Control Materials Competitive Strengths & Weaknesses

## **10 INDUSTRY CHAIN ANALYSIS**

- 10.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Industry Chain
- 10.2 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Upstream Analysis
  - 10.2.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Core Raw Materials
  - 10.2.2 Main Manufacturers of Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Core Raw Materials
- 10.3 Midstream Analysis
- 10.4 Downstream Analysis
- 10.5 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Mode
- 10.6 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Procurement Model
- 10.7 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Industry Sales Model and Sales Channels
  - 10.7.1 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Sales Model
  - 10.7.2 Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Typical Distributors

## **11 RESEARCH FINDINGS AND CONCLUSION**

## **12 APPENDIX**

12.1 Methodology

12.2 Research Process and Data Source

12.3 Disclaimer

## List Of Tables

### LIST OF TABLES

Table 1. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Region (2021, 2025 and 2032) & (USD Million)

Table 2. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Region (2021-2026) & (USD Million)

Table 3. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Region (2027-2032) & (USD Million)

Table 4. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share by Region (2021-2026)

Table 5. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share by Region (2027-2032)

Table 6. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Region (2021-2026) & (K Units)

Table 7. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Region (2027-2032) & (K Units)

Table 8. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share by Region (2021-2026)

Table 9. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share by Region (2027-2032)

Table 10. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Region (2021-2026) & (US\$/Unit)

Table 11. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Region (2027-2032) & (US\$/Unit)

Table 12. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Major Market Trends

Table 13. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (K Units)

Table 14. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption by Region (2021-2026) & (K Units)

Table 15. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Forecast by Region (2027-2032) & (K Units)

Table 16. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturer (2021-2026) & (USD Million)

- Table 17. Production Value Market Share of Key Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Producers in 2025
- Table 18. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Manufacturer (2021-2026) & (K Units)
- Table 19. Production Market Share of Key Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Producers in 2025
- Table 20. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Manufacturer (2021-2026) & (US\$/Unit)
- Table 21. Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Company Evaluation Quadrant
- Table 22. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Industry Rank of Major Manufacturers, Based on Production Value in 2025
- Table 23. Head Office and Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Site of Key Manufacturer
- Table 24. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Company Product Type Footprint
- Table 25. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market: Company Product Application Footprint
- Table 26. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Competitive Factors
- Table 27. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate New Entrant and Capacity Expansion Plans
- Table 28. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Mergers & Acquisitions Activity
- Table 29. United States VS China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)
- Table 30. United States VS China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Comparison, (2021 & 2025 & 2032) & (K Units)
- Table 31. United States VS China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Comparison, (2021 & 2025 & 2032) & (K Units)
- Table 32. United States Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (States, Country)
- Table 33. United States Based Manufacturers Automotive-grade Power Semiconductor

Modules Copper Needle Type Heat Dissipation Substrate Production Value, (2021-2026) & (USD Million)

Table 34. United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share (2021-2026)

Table 35. United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2026) & (K Units)

Table 36. United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share (2021-2026)

Table 37. China Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (Province, Country)

Table 38. China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value, (2021-2026) & (USD Million)

Table 39. China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share (2021-2026)

Table 40. China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, (2021-2026) & (K Units)

Table 41. China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share (2021-2026)

Table 42. Rest of World Based Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Manufacturers, Headquarters and Production Site (State, Country)

Table 43. Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value, (2021-2026) & (USD Million)

Table 44. Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share (2021-2026)

Table 45. Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production, (2021-2026) & (K Units)

Table 46. Rest of World Based Manufacturers Automotive-grade Power Semiconductor

Modules Copper Needle Type Heat Dissipation Substrate Production Market Share (2021-2026)

Table 47. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Type, (USD Million), 2021 & 2025 & 2032

Table 48. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Type (2021-2026) & (K Units)

Table 49. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Type (2027-2032) & (K Units)

Table 50. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Type (2021-2026) & (USD Million)

Table 51. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Type (2027-2032) & (USD Million)

Table 52. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Type (2021-2026) & (US\$/Unit)

Table 53. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Type (2027-2032) & (US\$/Unit)

Table 54. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturing Process, (USD Million), 2021 & 2025 & 2032

Table 55. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Manufacturing Process (2021-2026) & (K Units)

Table 56. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Manufacturing Process (2027-2032) & (K Units)

Table 57. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturing Process (2021-2026) & (USD Million)

Table 58. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Manufacturing Process (2027-2032) & (USD Million)

Table 59. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Manufacturing Process (2021-2026) & (US\$/Unit)

Table 60. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Manufacturing Process (2027-2032) & (US\$/Unit)

Table 61. World Automotive-grade Power Semiconductor Modules Copper Needle Type

Heat Dissipation Substrate Production Value by Vehicle, (USD Million), 2021 & 2025 & 2032

Table 62. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Vehicle (2021-2026) & (K Units)

Table 63. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Vehicle (2027-2032) & (K Units)

Table 64. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Vehicle (2021-2026) & (USD Million)

Table 65. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Vehicle (2027-2032) & (USD Million)

Table 66. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Vehicle (2021-2026) & (US\$/Unit)

Table 67. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Vehicle (2027-2032) & (US\$/Unit)

Table 68. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Application, (USD Million), 2021 & 2025 & 2032

Table 69. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Application (2021-2026) & (K Units)

Table 70. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production by Application (2027-2032) & (K Units)

Table 71. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Application (2021-2026) & (USD Million)

Table 72. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Application (2027-2032) & (USD Million)

Table 73. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Application (2021-2026) & (US\$/Unit)

Table 74. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price by Application (2027-2032) & (US\$/Unit)

Table 75. Huangshan Gooe Basic Information, Manufacturing Base and Competitors

Table 76. Huangshan Gooe Major Business

Table 77. Huangshan Gooe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 78. Huangshan Gooe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 79. Huangshan Gooe Recent Developments/Updates

Table 80. Huangshan Gooze Competitive Strengths & Weaknesses

Table 81. Heatsink Advanced Materials Basic Information, Manufacturing Base and Competitors

Table 82. Heatsink Advanced Materials Major Business

Table 83. Heatsink Advanced Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 84. Heatsink Advanced Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 85. Heatsink Advanced Materials Recent Developments/Updates

Table 86. Heatsink Advanced Materials Competitive Strengths & Weaknesses

Table 87. Kunshan Gootage Thermal Technology Basic Information, Manufacturing Base and Competitors

Table 88. Kunshan Gootage Thermal Technology Major Business

Table 89. Kunshan Gootage Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 90. Kunshan Gootage Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 91. Kunshan Gootage Thermal Technology Recent Developments/Updates

Table 92. Kunshan Gootage Thermal Technology Competitive Strengths & Weaknesses

Table 93. Dana Incorporated Basic Information, Manufacturing Base and Competitors

Table 94. Dana Incorporated Major Business

Table 95. Dana Incorporated Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 96. Dana Incorporated Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 97. Dana Incorporated Recent Developments/Updates

Table 98. Dana Incorporated Competitive Strengths & Weaknesses

Table 99. Jentech Precision Industrial Basic Information, Manufacturing Base and Competitors

Table 100. Jentech Precision Industrial Major Business

Table 101. Jentech Precision Industrial Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 102. Jentech Precision Industrial Automotive-grade Power Semiconductor

Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 103. Jentech Precision Industrial Recent Developments/Updates

Table 104. Jentech Precision Industrial Competitive Strengths & Weaknesses

Table 105. Amulaire Thermal Technology Basic Information, Manufacturing Base and Competitors

Table 106. Amulaire Thermal Technology Major Business

Table 107. Amulaire Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 108. Amulaire Thermal Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 109. Amulaire Thermal Technology Recent Developments/Updates

Table 110. Amulaire Thermal Technology Competitive Strengths & Weaknesses

Table 111. TAIWA CO., Ltd. Basic Information, Manufacturing Base and Competitors

Table 112. TAIWA CO., Ltd. Major Business

Table 113. TAIWA CO., Ltd. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 114. TAIWA CO., Ltd. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 115. TAIWA CO., Ltd. Recent Developments/Updates

Table 116. TAIWA CO., Ltd. Competitive Strengths & Weaknesses

Table 117. Wieland Microcool Basic Information, Manufacturing Base and Competitors

Table 118. Wieland Microcool Major Business

Table 119. Wieland Microcool Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

Table 120. Wieland Microcool Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 121. Wieland Microcool Recent Developments/Updates

Table 122. Wieland Microcool Competitive Strengths & Weaknesses

Table 123. Jiangyin Saiying Electron Basic Information, Manufacturing Base and Competitors

Table 124. Jiangyin Saiying Electron Major Business

Table 125. Jiangyin Saiying Electron Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services

- Table 126. Jiangyin Saiying Electron Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 127. Jiangyin Saiying Electron Recent Developments/Updates
- Table 128. Jiangyin Saiying Electron Competitive Strengths & Weaknesses
- Table 129. Suzhou Haoli Electronic Technology Basic Information, Manufacturing Base and Competitors
- Table 130. Suzhou Haoli Electronic Technology Major Business
- Table 131. Suzhou Haoli Electronic Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
- Table 132. Suzhou Haoli Electronic Technology Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 133. Suzhou Haoli Electronic Technology Recent Developments/Updates
- Table 134. Suzhou Haoli Electronic Technology Competitive Strengths & Weaknesses
- Table 135. Sitritec Thermal Control Materials Basic Information, Manufacturing Base and Competitors
- Table 136. Sitritec Thermal Control Materials Major Business
- Table 137. Sitritec Thermal Control Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Product and Services
- Table 138. Sitritec Thermal Control Materials Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 139. Sitritec Thermal Control Materials Recent Developments/Updates
- Table 140. Sitritec Thermal Control Materials Competitive Strengths & Weaknesses
- Table 141. Global Key Players of Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Upstream (Raw Materials)
- Table 142. Global Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Typical Customers
- Table 143. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Typical Distributors

## List Of Figures

### LIST OF FIGURES

- Figure 1. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Picture
- Figure 2. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value: 2021 & 2025 & 2032, (USD Million)
- Figure 3. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value and Forecast (2021-2032) & (USD Million)
- Figure 4. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032) & (K Units)
- Figure 5. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Average Price (2021-2032) & (US\$/Unit)
- Figure 6. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share by Region (2021-2032)
- Figure 7. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share by Region (2021-2032)
- Figure 8. North America Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032) & (K Units)
- Figure 9. Europe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032) & (K Units)
- Figure 10. China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032) & (K Units)
- Figure 11. Japan Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production (2021-2032) & (K Units)
- Figure 12. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Market Drivers
- Figure 13. Factors Affecting Demand
- Figure 14. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)
- Figure 15. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Market Share by Region (2021-2032)
- Figure 16. United States Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)
- Figure 17. China Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)
- Figure 18. Europe Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)

Figure 19. Japan Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)

Figure 20. South Korea Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)

Figure 21. ASEAN Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)

Figure 22. India Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption (2021-2032) & (K Units)

Figure 23. Producer Shipments of Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate by Manufacturer Revenue (\$MM) and Market Share (%): 2025

Figure 24. Global Four-firm Concentration Ratios (CR4) for Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Markets in 2025

Figure 25. Global Four-firm Concentration Ratios (CR8) for Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Markets in 2025

Figure 26. United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value Market Share Comparison (2021 & 2025 & 2032)

Figure 27. United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share Comparison (2021 & 2025 & 2032)

Figure 28. United States VS China: Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Consumption Market Share Comparison (2021 & 2025 & 2032)

Figure 29. United States Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share 2025

Figure 30. China Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share 2025

Figure 31. Rest of World Based Manufacturers Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Market Share 2025

Figure 32. World Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Production Value by Type, (USD Million), 2021 & 2025 & 2032

Figure 33. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Type in 2025

Figure 34. IGBT Module

Figure 35. SiC MOSFET Module

Figure 36. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Market Share by Type (2021-2032)

Figure 37. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Type (2021-2032)

Figure 38. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Average Price by Type (2021-2032) & (US\$/Unit)

Figure 39. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value by Manufacturing Process, (USD Million), 2021 & 2025 & 2032

Figure 40. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Manufacturing Process in 2025

Figure 41. Integral Cold Forging

Figure 42. Welding Assembly Forming

Figure 43. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Market Share by Manufacturing Process (2021-2032)

Figure 44. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Manufacturing Process (2021-2032)

Figure 45. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Average Price by Manufacturing Process (2021-2032) & (US\$/Unit)

Figure 46. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value by Vehicle, (USD Million), 2021 & 2025 & 2032

Figure 47. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Vehicle in 2025

Figure 48. Passenger Car

Figure 49. Commercial Vehicle

Figure 50. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Market Share by Vehicle (2021-2032)

Figure 51. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Vehicle (2021-2032)

Figure 52. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Average Price by Vehicle (2021-2032) & (US\$/Unit)

Figure 53. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value by Application, (USD Million), 2021 & 2025 & 2032

Figure 54. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Application in 2025

Figure 55. BEV

Figure 56. PHEV

Figure 57. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Market Share by Application (2021-2032)

Figure 58. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Production Value Market Share by Application (2021-2032)

Figure 59. World Automotive-grade Power Semiconductor Modules Copper Needle

Type Heat Dissipation Substrate Average Price by Application (2021-2032) & (US\$/Unit)

Figure 60. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Industry Chain

Figure 61. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Procurement Model

Figure 62. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Sales Model

Figure 63. Automotive-grade Power Semiconductor Modules Copper Needle Type Heat Dissipation Substrate Sales Channels, Direct Sales, and Distribution

Figure 64. Methodology

Figure 65. Research Process and Data Source

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